

(PRIOR ART)

FIG. 1

Component (e.g., a LGA component) 106

Interposer 110

Substrate Electrical Contact Area 108

Substrate (e.g., a printed circuit board) 104

Substrate Electrical Contact Area 102 Interposer 212

Capacitor Plate 214

v1		gnd		v 2
Pad		Pad		Pad
302		304		340
	Dielectric Layer 306		Dielectric Layer	306
0.003	Ground Plane 308		Ground Plane 3	08
		Via	Dielectric Layer	310
	Power Plane 312	336	Power Plane 3	12
Via	Dielectric Layer 314		Dielectric Layer	314 Via
332	Ground Plane 316		Ground Plane 3	16 338
	Dielectric Layer 318		Dielectric Layer	318
	Power Plane 320		Power Plane 32	20
	Dielectric Layer 322		Dielectric Layer	322
	Ground Plane 324		Ground Plane 3	24
	Dielectric Layer 326		Dielectric Layer	326
	Power Plane 328		Power Plane 32	28
	Dielectric Layer 330		Dielectric Layer	330
Pad		Pad		Pad
342		344		346

FIG. 3

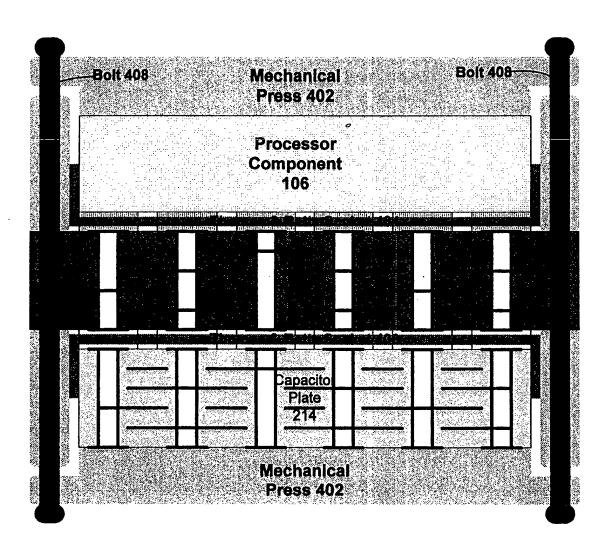


FIG. 4

